

SOT1921-5(D)

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.9 mm body

1 July 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN24
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	10-06-2020
Manufacturer package code	98ASA01626D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
package height	1.85	1.9	1.95	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	24	-	



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2 Package outline

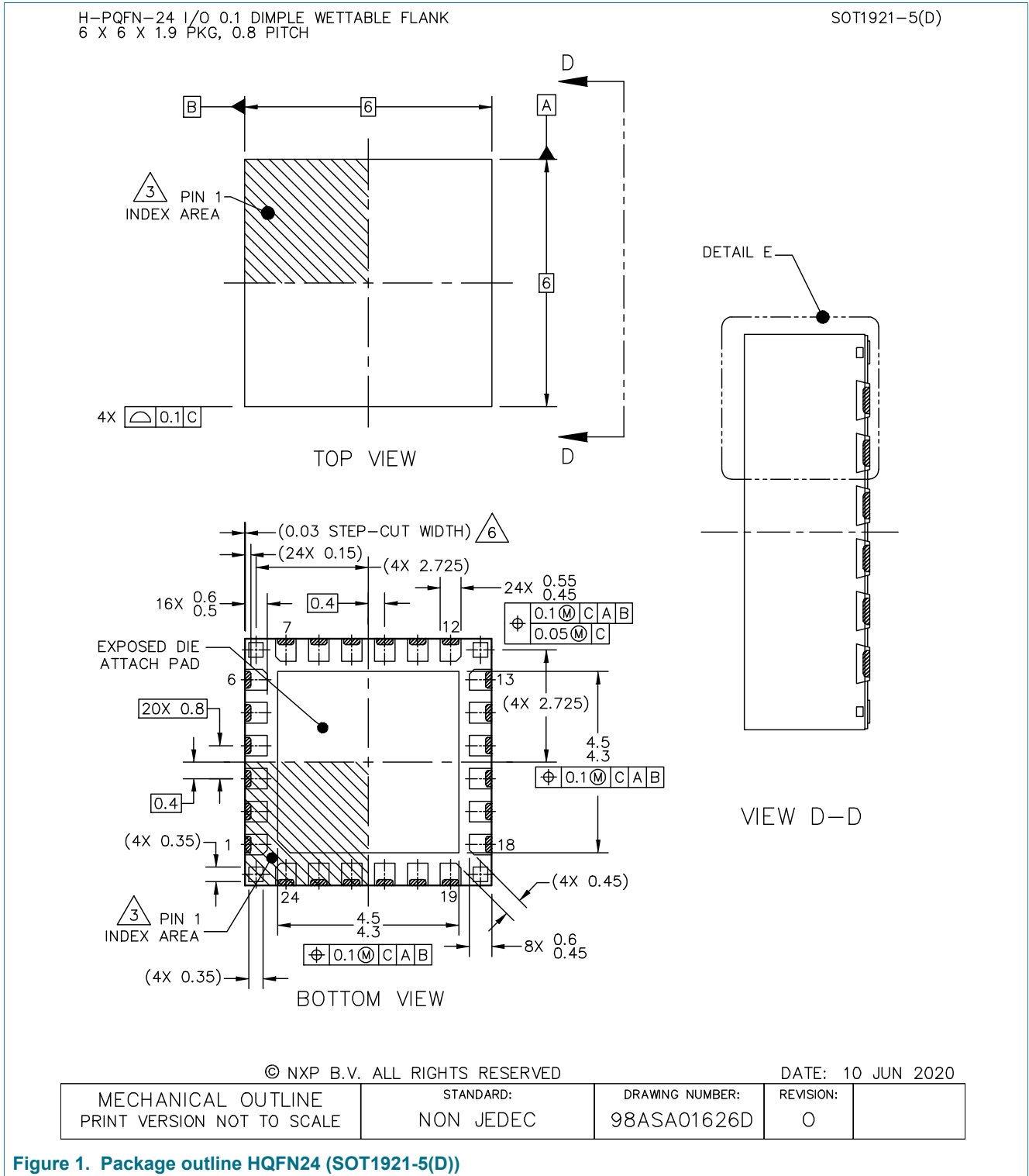


Figure 1. Package outline HQFN24 (SOT1921-5(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.9 mm body

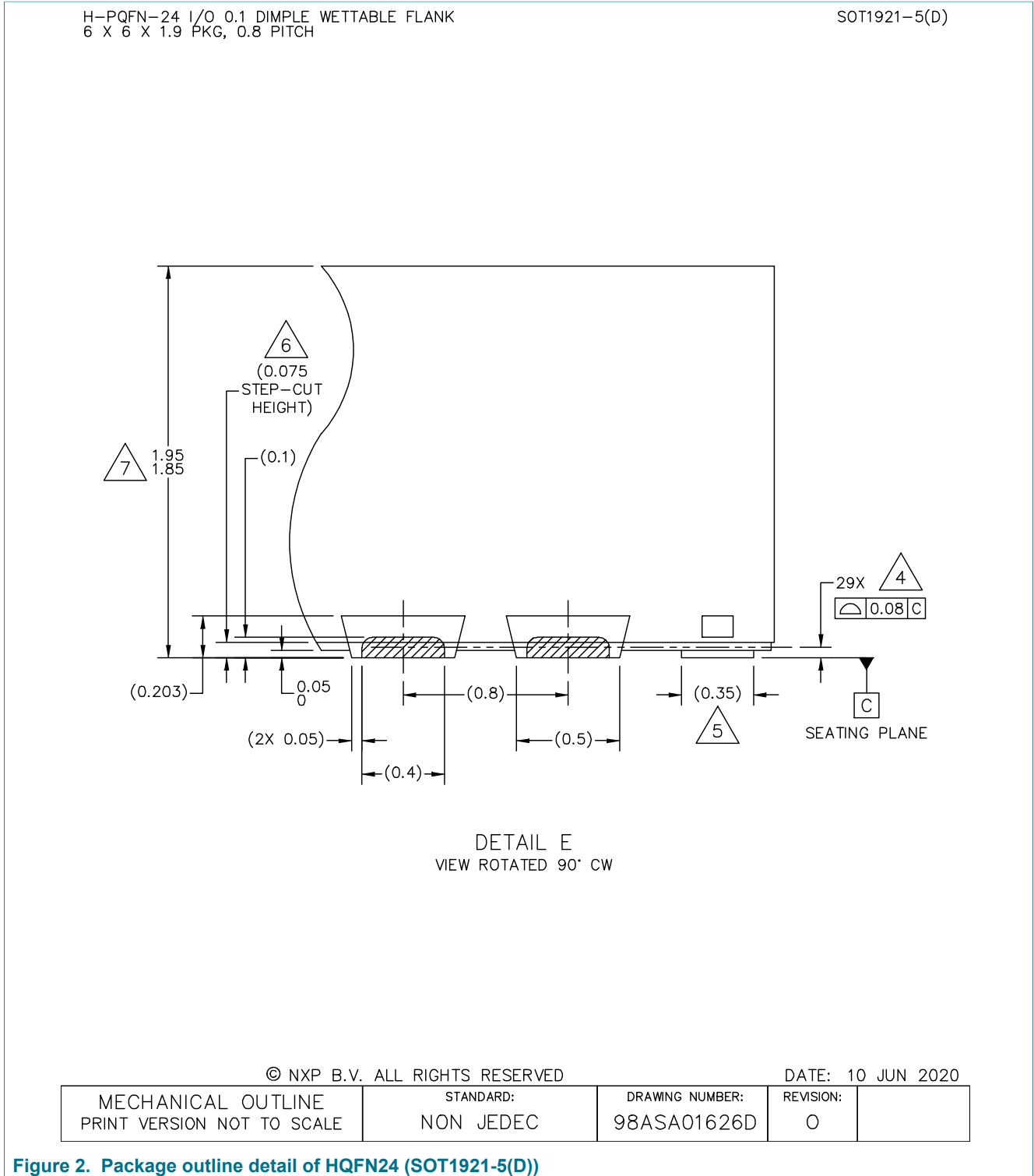


Figure 2. Package outline detail of HQFN24 (SOT1921-5(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.9 mm body

3 Soldering

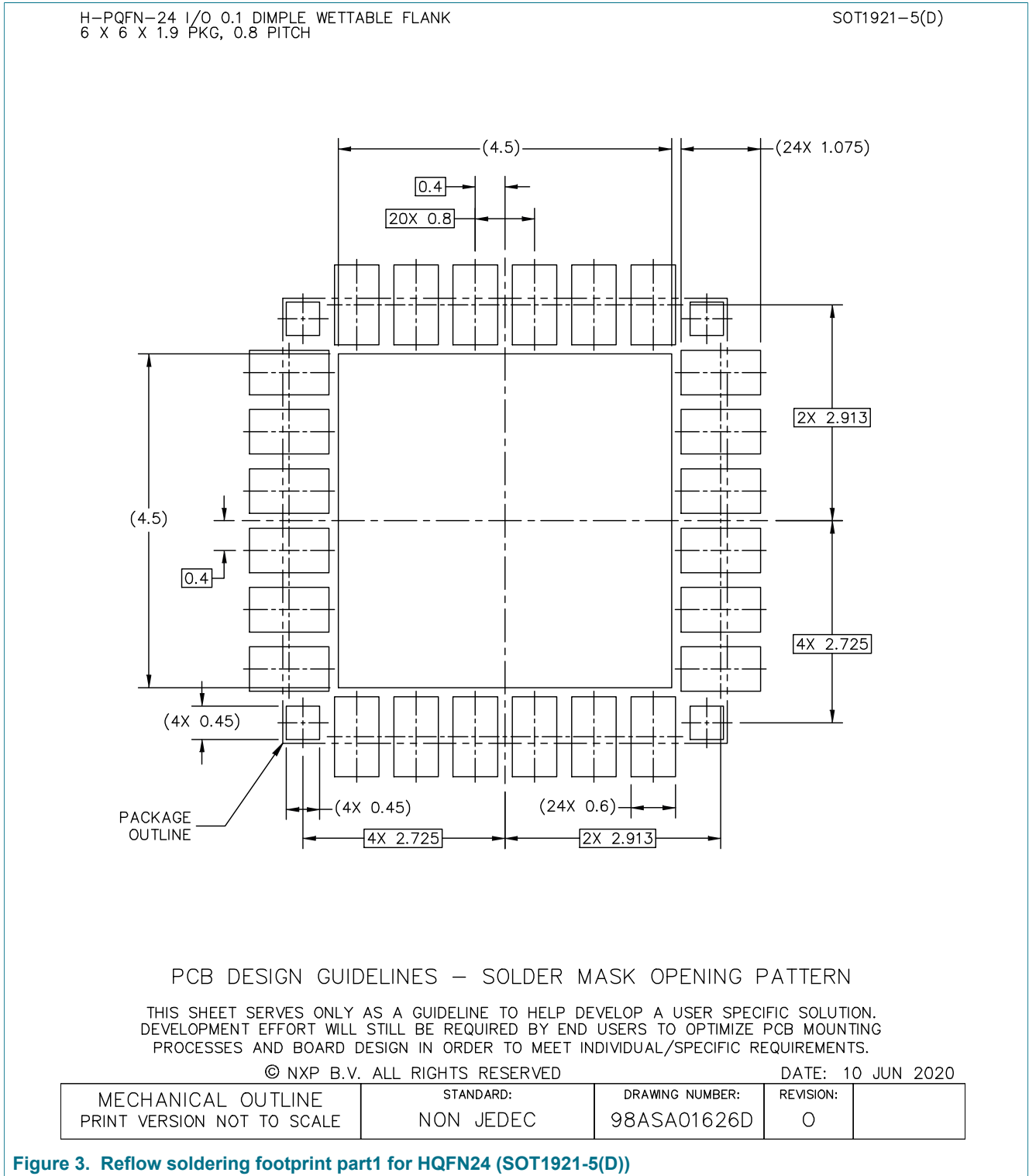
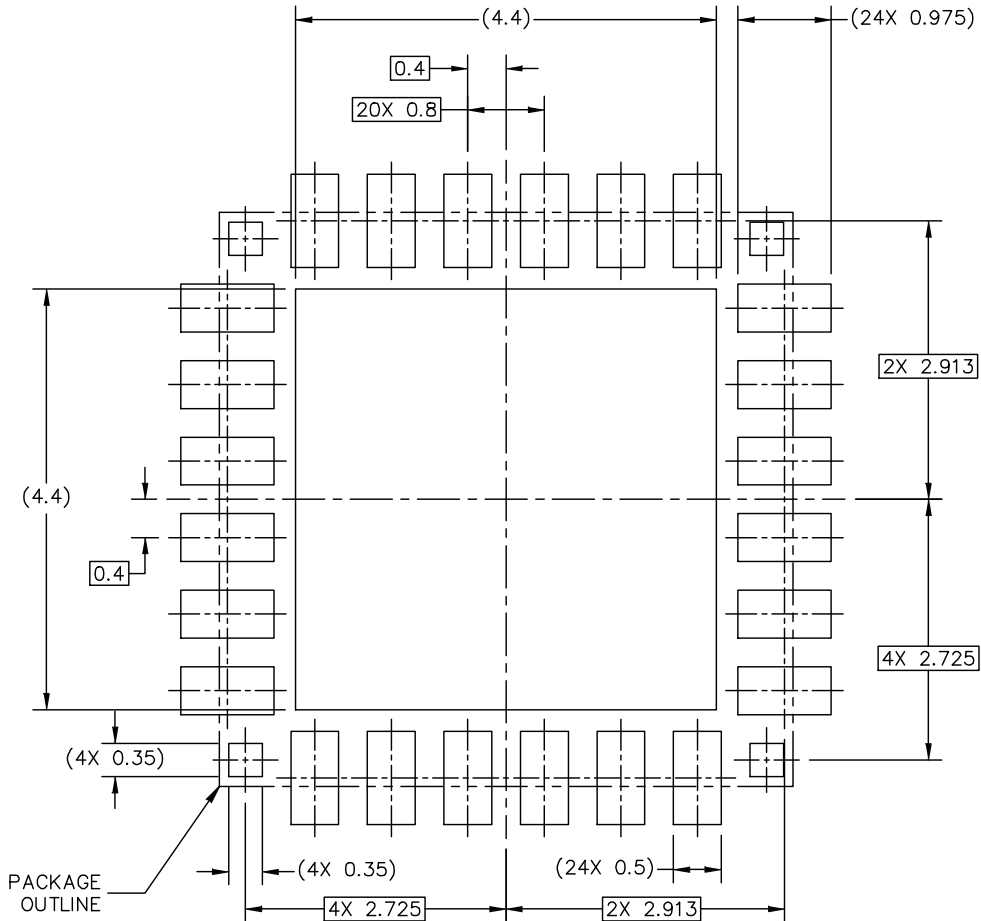


Figure 3. Reflow soldering footprint part1 for HQFN24 (SOT1921-5(D))

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H-PQFN-24 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 1.9 PKG, 0.8 PITCH

SOT1921-5(D)



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Figure 4. Reflow soldering footprint part2 for HQFN24 (SOT1921-5(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.9 mm body

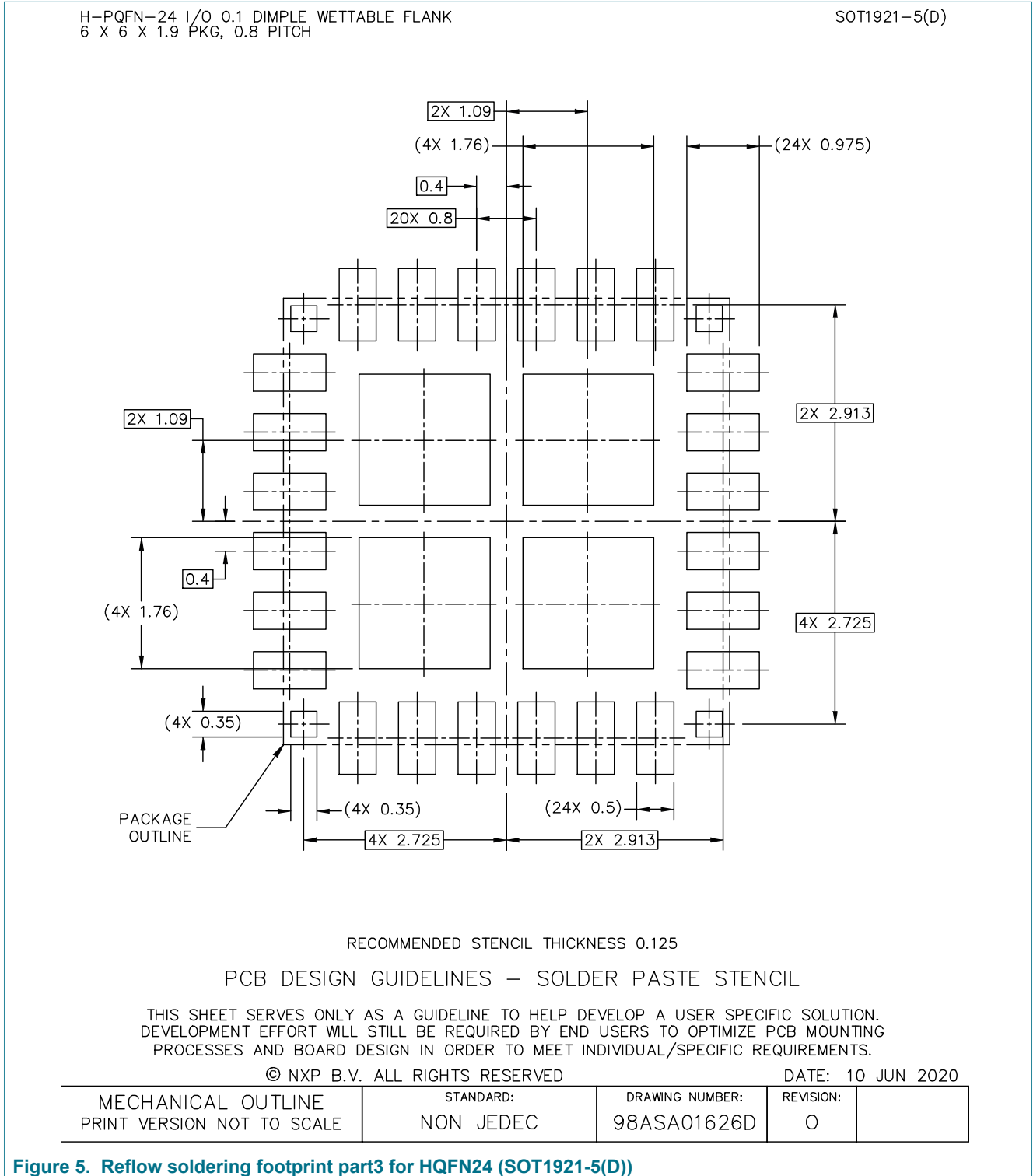


Figure 5. Reflow soldering footprint part3 for HQFN24 (SOT1921-5(D))

HQFN24, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.9 mm body

H-PQFN-24 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 1.9 PKG, 0.8 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. ANCHORING PADS.
6. STEP-CUT IS APPLIED FOR BURR REMOVAL ONLY.
7. SPUTTER LAYER OF STAINLESS STEEL SUS316 IS INCLUDED IN THE TOP SIDE SURFACE.

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Figure 6. Package outline note HQFN24 (SOT1921-5(D))

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